Electronic Acknowledgement Receipt				
EFS ID:	1164114			
Application Number:	10731995			
Confirmation Number:	5870			
Title of Invention:	PACKAGES FOR SEMICONDUCTOR DIE			
First Named Inventor:	Todd O. Bolken			
Customer Number:	23720			
Filer:	J. Mike Amerson/Mary Paul			
Filer Authorized By:	J. Mike Amerson			
Attorney Docket Number:	6047-67518			
Receipt Date:	21-AUG-2006			
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Application Type:	Utility			
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1	Issue Fee Payment Recorded	Fees_Transmittal.pdf	63479	no	1

Warnings:	
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Total Files Size (in bytes):	63479

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.